

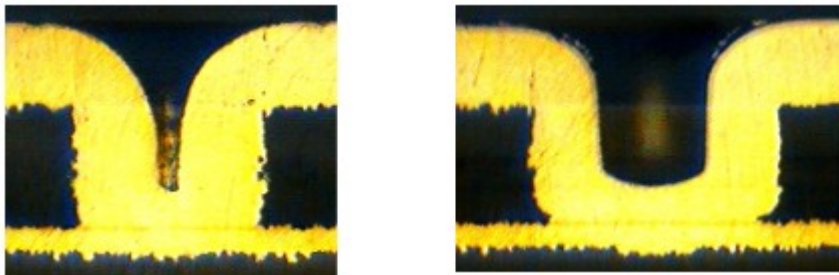
## Minimum blind via

Minimum blind via – a blind via is a connection which does not pass through the printed circuit board and is created between outer and inner layers.

If the aspect ratio is insufficient, i.e. if the diameter of the drill is smaller than the depth of the hole, the stacking of blind vias is also used (so-called stacked vias).

At Brandner Electronics, as at most Japanese companies that manufacture PCBs, blind vias are manufactured mechanically which ensures a higher quality of vias than laser technology.

The minimum measure shows the diameter of the drill bit used for drilling the hole. After plating, the diameter of the blind via decreases by up to 50  $\mu$ .



Cross sections, i.e. microsections of blind vias with different diameters.